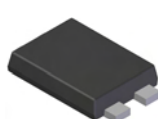


Features

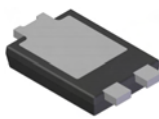
- Guard Ring Die Construction for Transient Protection
- High Surge Current Capability
- Low Leakage Current
- Low Power Loss, High Efficiency
- For Use in High Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- High Forward Surge Current Capability
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **"Green" Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

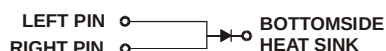
- Case: PowerDI[®]5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 **(e3)**
- Polarity: See Diagram
- Weight: 0.094 grams (approximate)



Top View



Bottom View



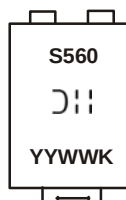
Note: Pins Left & Right must be electrically connected at the printed circuit board.

Ordering Information (Note 2)

Part Number	Case	Packaging
PDS560-13	PowerDI [®] 5	5000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
2. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



S560 = Product type marking code
 ⌋|| = Manufacturers' code marking
 YYWW = Date code marking
 YY = Last two digits of year (ex: 05 for 2005)
 WW = Week code (01 – 53)
 K = Factory Designator

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	60	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	42	V
Average Rectified Output Current (See figure 4)	I _O	5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load	I _{FSM}	150	A

Thermal Characteristics

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point	R _{θJS}	—	2.0	°C/W
Thermal Resistance Junction to Ambient Air (Note 3) T _A = 25°C	R _{θJA}	95	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 4) T _A = 25°C	R _{θJA}	70	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 5) T _A = 25°C	R _{θJA}	50	—	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150		°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	60	—	—	V	I _R = 0.2mA
Forward Voltage	V _F	—	0.61	0.67	V	I _F = 5A, T _S = 25°C
		—	0.54	0.60		I _F = 5A, T _S = 125°C
		—	0.71	0.77		I _F = 8A, T _S = 25°C
		—	—	0.68		I _F = 8A, T _S = 125°C
Reverse Leakage Current (Note 6)	I _R	—	4	150	μA	T _S = 25°C, V _R = 60V
		—	—	15	mA	T _S = 100°C, V _R = 60V
		—	2	30	mA	T _S = 125°C, V _R = 60V

- Notes:
3. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
 4. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
 5. Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.
 6. Short duration pulse test used to minimize self-heating effect.

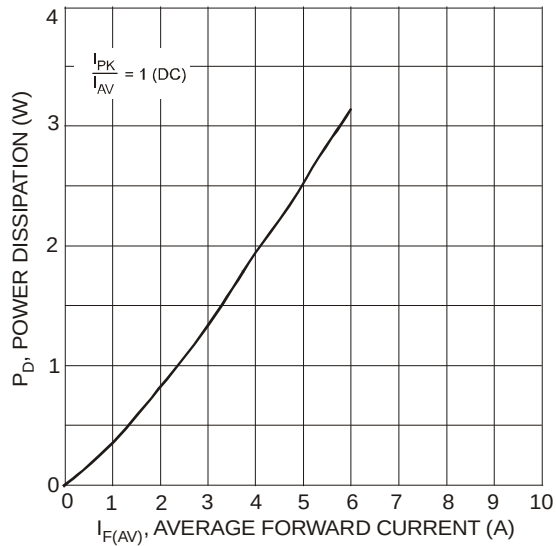


Fig. 1 Forward Power Dissipation

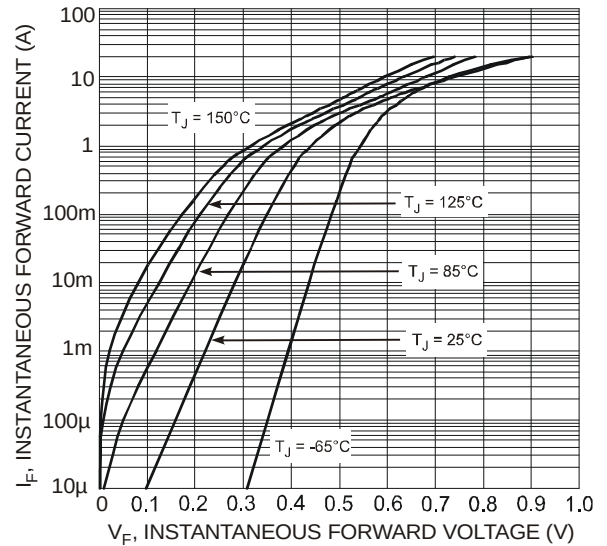


Fig. 2 Typical Forward Characteristics

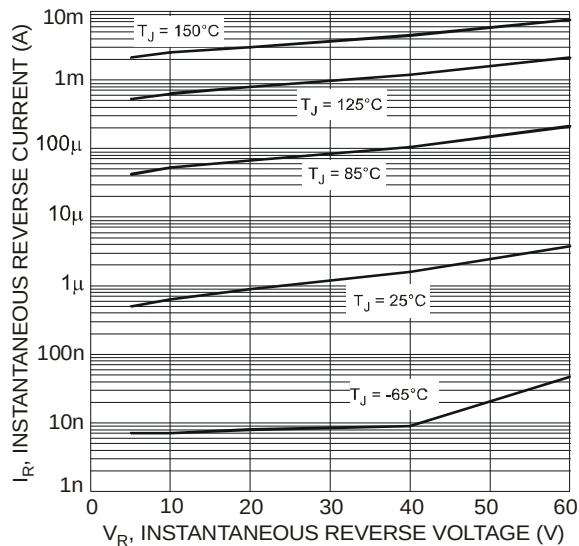


Fig. 3 Typical Reverse Characteristics

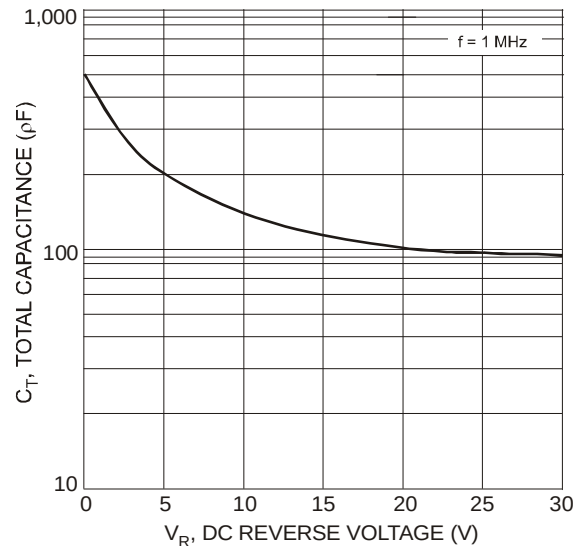


Fig. 4 Total Capacitance vs. Reverse Voltage

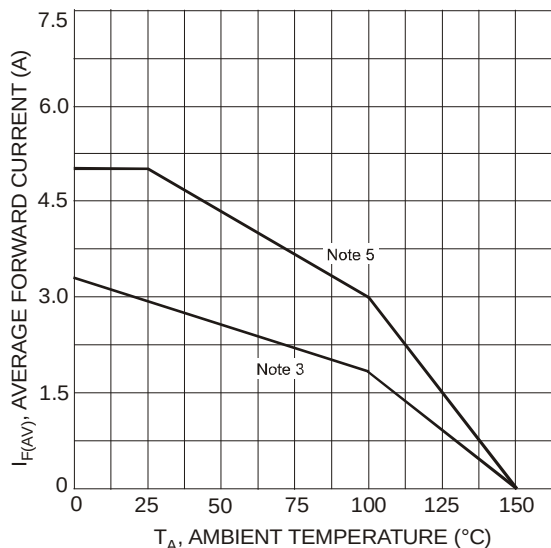


Fig. 5 Forward Current Derating Curve

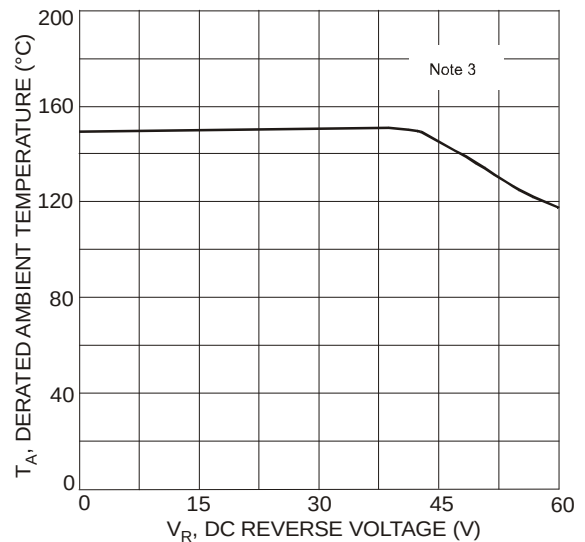
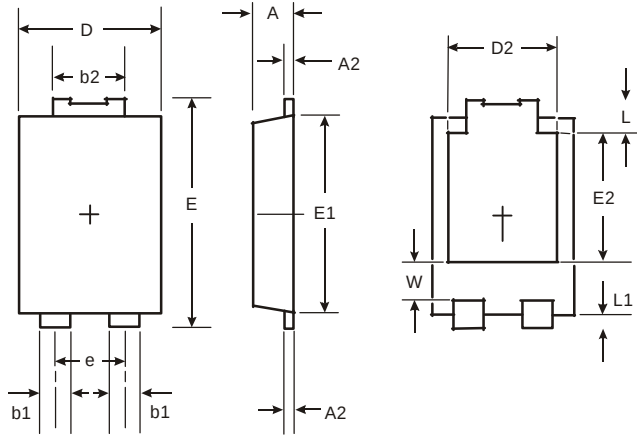


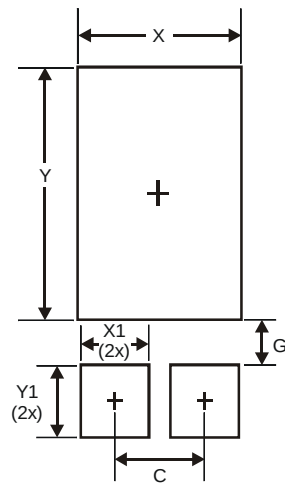
Fig. 6 Operating Temperature Derating

Package Outline Dimensions



PowerDI® 5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

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